

## COMPONENT PACKAGING APPARATUS, SYSTEMS, AND METHODS

### Abstract of the Disclosure

Dielectric materials comprising release agents are described. Also described are a process for improving the processability of dielectric materials during hot embossing, substrates prepared by hot embossing, and integrated-circuit packages  
5 comprising the improved substrate.

"Express Mail" mailing label number: EV370238767US

Date of Deposit: December 31, 2003

This paper or fee is being deposited on the date indicated above with the United States Postal Service pursuant to 37 CFR 1.10, and is addressed to the Commissioner for Patents, Mail Stop Patent Application, P.O. Box 1450, Alexandria, VA 22313-1450.